

SCES085I-AUGUST 1996-REVISED OCTOBER 2004

FEATURES	DGG, DGV, OR	
 Member of the Texas Instruments Widebus™ Family 	(TOP V	
Operates From 1.65 V to 3.6 V		56 0E4
• Max t _{pd} of 4.4 ns at 3.3 V	1B1 🛛 2	55 8B1
• \pm 12-mA Output Drive at 3.3 V	1B2 🛛 3	54 8B2
•	GND 🛛 4	53 GND
 Output Ports Have Equivalent 26-Ω Series Resistors, So No External Resistors Are 	1B3 🛛 5	52 0 8B3
Required	1B4 🛛 6	51 8B4
•	V _{CC} 7	50 V _{CC}
Bus Hold on Data Inputs Eliminates the Need for External Bullum/Bulldown Basisters	1A 🛛 8	49 0 8A
for External Pullup/Pulldown Resistors	2B1 9	48 7B1
Latch-Up Performance Exceeds 250 mA Per	2B2 🛛 10	47 7B2
JESD 17	GND 11	46 GND
	2B3 12	45 7B3
DESCRIPTION/ORDERING INFORMATION	2B4 13	44 7B4
This 1-bit to 4-bit address driver is designed for	2A 14	43 7A
1.65-V to 3.6-V V _{CC} operation.	3A 15	42 6A
The SN74ALVCH162344 is used in applications in	3B1 [] 16	41 6B1
which four separate memory locations must be	3B2 17	40 6B2
addressed by a single address.	GND 18	39 GND
The outputs, which are designed to sink up to 12 mA,	3B3 [] 19	38 6B3
include equivalent 26- Ω resistors to reduce overshoot	3B4 🛛 20 4A 🗍 21	37 6B4 36 5A
and undershoot.		E
To ensure the bigh impedance state during neuron up	V _{CC} [] 22 4B1 [] 23	35 V _{CC} 34 5B1
To ensure the high-impedance state during power up or power down, the output-enable (OE) inputs should	4B1 [] 23 4B2 [] 24	34] 5B1 33] 5B2
be tied to V_{CC} through a pullup resistor; the minimum	GND 25	32 GND
value of the resistor is determined by the	4B3 26	31 5B3
current-sinking capability of the driver.	4B3 [] 20 4B4 [] 27	30 5B4
Active bus-hold circuitry holds unused or undriven	0E2 28	29 0E3
	<u> </u>	

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP - DL	Tube	SN74ALVCH162344DL	ALVCH162344
	550P - DL	Tape and reel	SN74ALVCH162344DLR	ALVCH102344
	TSSOP - DGG	Tape and reel	SN74ALVCH162344GR	ALVCH162344
	TVSOP - DGV	Tape and reel	SN74ALVCH162344VR	VH2344

Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at (1) www.ti.com/sc/package.



recommended.

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inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not

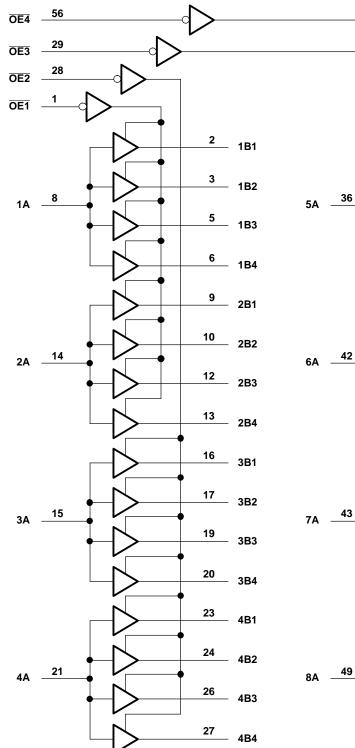
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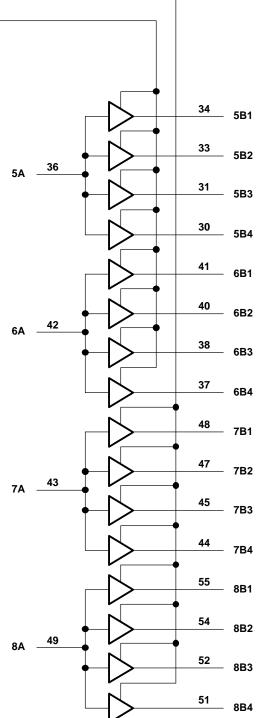
A-TO-B FUNCTION TABLE

INPL	JTS	OUTPUT
ŌĒ	Α	Bn
L	Н	Н
L	L	L
Н	Х	Z

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LOGIC DIAGRAM (POSITIVE LOGIC)



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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range ⁽²⁾		-0.5	4.6	V
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through each V _{CC} or GN	D		±100	mA
		DGG package		64	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGV package		48	°C/W
		DL package		56	
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		1.65	3.6	V
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
V _{IH}	High-level input voltage	V_{CC} = 2.3 V to 2.7 V	1.7		V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	2		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
V _{IL}	Low-level input voltage	V_{CC} = 2.3 V to 2.7 V		0.7	V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$		0.8	
VI	Input voltage		0	V _{CC}	V
Vo	Output voltage		0	V _{CC}	V
	High-level output current	V _{CC} = 1.65 V		-2	mA
		$V_{CC} = 2.3 V$		-6	
I _{OH}		$V_{CC} = 2.7 V$		-8	
		$V_{CC} = 3 V$		-12	
		V _{CC} = 1.65 V		2	
I _{OL}	Low lovel output ourrent	$V_{CC} = 2.3 V$		6	~ ^
	Low-level output current	$V_{CC} = 2.7 V$		8	mA
		$V_{CC} = 3 V$		12	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-40	85	°C

 All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾	MAX	UNIT	
	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2				
	I _{OH} = -2 mA	1.65 V	1.2				
	I _{OH} = -4 mA	2.3 V	1.9				
V _{OH}		2.3 V	1.7			V	
	$I_{OH} = -6 \text{ mA}$	3 V	2.4				
	I _{OH} = -8 mA	2.7 V	2				
	I _{OH} = -12 mA	3 V	2				
	I _{OL} = 100 μA	1.65 V to 3.6 V			0.2		
	I _{OL} = 2 mA	1.65 V			0.45		
	I _{OL} = 4 mA	2.3 V			0.4		
V _{OL}		2.3 V			0.55	V	
	I _{OL} = 6 mA	3 V			0.55		
	I _{OL} = 8 mA	2.7 V			0.6]	
	I _{OL} = 12 mA	3 V			0.8		
l _l	$V_{I} = V_{CC} \text{ or } GND$	3.6 V			±5	μA	
	V _I = 0.58 V	1.65 V	25				
	V _I = 1.07 V	1.65 V	-25				
	V _I = 0.7 V	2.3 V	45				
I _{I(hold)}	V _I = 1.7 V	2.3 V	-45			μA	
	V _I = 0.8 V	3 V	75				
	V ₁ = 2 V	3 V	-75				
	$V_1 = 0$ to 3.6 V ⁽²⁾	3.6 V			±500		
l _{oz}	$V_{O} = V_{CC}$ or GND	3.6 V			±10	μΑ	
I _{CC}	$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	3.6 V			40	μA	
Δl _{CC}	One input at V_{CC} - 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μΑ	
Control inputs		221		2.5		- 5	
C _i Data inputs	$-V_{I} = V_{CC} \text{ or } GND$	3.3 V		3.5		рF	
C _o Outputs	$V_{O} = V_{CC}$ or GND	3.3 V		4		pF	

(1)

All typical values are at V_{CC} = 3.3 V, T_A = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to (2) another.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER		TO	V _{CC} = 1.8 V	$ \begin{array}{c} V_{CC} = 2.5 \ V \\ \pm \ 0.2 \ V \end{array} \hspace{0.5cm} V_{CC} = 2.7 \ V \end{array} $		V_{CC} = 2.5 V ± 0.2 V		$v_{cc} = 1.8 V$ $V_{cc} = 2.5 V$ $V_{cc} = 2.7 V$ $V_{cc} = \frac{1.8 V}{\pm 0.2 V}$ $V_{cc} = 2.7 V$ $\frac{V_{cc}}{\pm 0.2 V}$	$V_{CC} = 2.5 \text{ V}$ $V_{CC} = 2.7 \text{ V}$ $V_{CC} = 3.3 \text{ V}$ $\pm 0.2 \text{ V}$ $V_{CC} = 0.3 \text{ V}$ $\pm 0.3 \text{ V}$		8.3 V V	UNIT
	(INPUT) (OUTPUT)	(INPUT) (OUTPUT) TYP MIN I	MAX	MIN	MAX	MIN	MAX					
t _{pd}	А	В	(1)	1	4.9		5.1	1.4	4.4	ns		
t _{en}	OE	В	(1)	1	6.4		6.6	1.2	5.7	ns		
t _{dis}	OE	В	(1)	1	5.4		4.7	1.2	4.5	ns		
t _{sk(0)} ⁽²⁾									0.35	ns		
t _{sk(0)} ⁽³⁾									0.5	ns		

This information was not available at the time of publication. (1)

(2) Skew between outputs of the same bank and same package (same transition)

(3)Skew between outputs of all banks of same package (A1-A8 tied together)



OPERATING CHARACTERISTICS

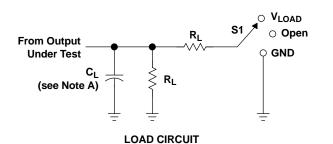
 $T_A = 25^{\circ}C$

	PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
C	Power dissipation	Outputs enabled	C = 0 pE f = 10 MHz	(1)	68	82	٥F
Cpd	capacitance	Outputs disabled	C _L = 0 pF, f = 10 MHz	(1)	12	14	рг

(1) This information was not available at the time of publication.

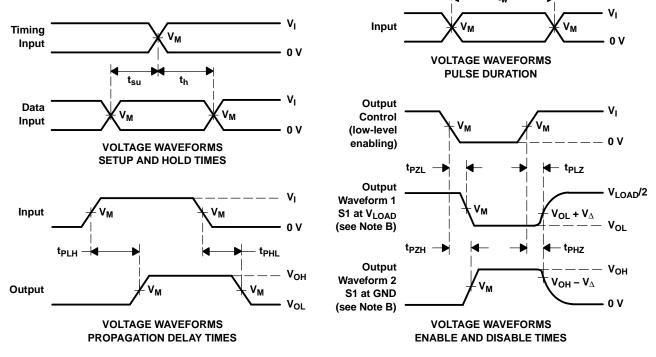
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PARAMETER MEASUREMENT INFORMATION



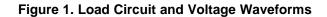
TEST	S1
t _{pd}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

Γ	V	IN	PUT	V	v	6	Р	v
	V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	C∟	RL	V_{Δ}
Γ	1.8 V \pm 0.15 V	V _{CC}	≤ 2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
	2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
	2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
	3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Ω = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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